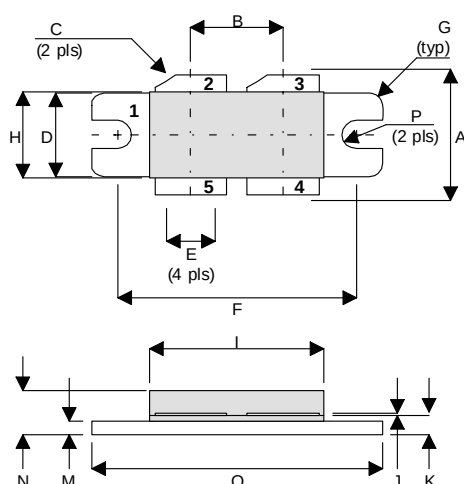


MECHANICAL DATA

D1

PIN 1	SOURCE (COMMON)	PIN 2	DRAIN 1
PIN 3	DRAIN 2	PIN 4	GATE 2
PIN 5	GATE 1		

DIM	Millimetres	Tol.	Inches	Tol.
A	15.24	0.50	0.600	0.020
B	10.80	0.13	0.425	0.005
C	45°	5°	45°	5°
D	9.78	0.13	0.385	0.005
E	8.38	0.13	0.330	0.005
F	27.94	0.13	1.100	0.005
G	1.52R	0.13	0.060R	0.005
H	10.16	0.15	0.400	0.006
I	21.84	0.23	0.860	0.009
J	0.10	0.02	0.004	0.001
K	1.96	0.13	0.077	0.005
M	1.02	0.13	0.040	0.005
N	4.45	0.38	0.175	0.015
O	34.04	0.13	1.340	0.005
P	1.63R	0.13	0.064R	0.005

GOLD METALLISED **MULTI-PURPOSE SILICON** **DMOS RF FET** **350W – 50V – 175MHz** **PUSH-PULL**

FEATURES

- SUITABLE FOR BROAD BAND APPLICATIONS
- SIMPLE BIAS CIRCUITS
- ULTRA-LOW THERMAL RESISTANCE
- BeO FREE
- LOW Crss
- HIGH GAIN – 20 dB MINIMUM

APPLICATIONS

- VHF/UHF COMMUNICATIONS
from 1 MHz to 400 MHz

ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}C$ unless otherwise stated)

P_D	Power Dissipation	875W (438W -A Version)
BV_{DSS}	Drain – Source Breakdown Voltage *	125V
BV_{GSS}	Gate – Source Breakdown Voltage*	$\pm 20V$
$I_{D(sat)}$	Drain Current*	21A
T_{stg}	Storage Temperature	-65 to $150^{\circ}C$
T_j	Maximum Operating Junction Temperature	$200^{\circ}C$

* Per Side

Semelab Plc reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by Semelab is believed to be both accurate and reliable at the time of going to press. However Semelab assumes no responsibility for any errors or omissions discovered in its use. Semelab encourages customers to verify that datasheets are current before placing orders.

ELECTRICAL CHARACTERISTICS (T_{case} = 25°C unless otherwise stated)

Parameter	Test Conditions	Min.	Typ.	Max.	Unit
PER SIDE					
B _V DSS	Drain–Source Breakdown Voltage V _{GS} = 0 I _D = 100mA	125			V
I _D DSS	Zero Gate Voltage Drain Current V _{DS} = 50V V _{GS} = 0			7	mA
I _G DSS	Gate Leakage Current V _{GS} = 20V V _{DS} = 0			1	μA
V _{GS} (th)	Gate Threshold Voltage* I _D = 10mA V _{DS} = V _{GS}	1		7	V
g _{fs}	Forward Transconductance* V _{DS} = 10V I _D = 3.5A	5.6			mhos
V _{GS} (th)match	Gate Threshold Voltage Matching Between Sides I _D = 10mA V _{DS} = V _{GS}			0.1	V
TOTAL DEVICE					
G _{PS}	Common Source Power Gain P _O = 350W	20			dB
η	Drain Efficiency V _{DS} = 50V I _{DQ} = 1.4A	60			%
VSWR	Load Mismatch Tolerance f = 175MHz	20:1			—
PER SIDE					
C _{iss}	Input Capacitance V _{DS} = 50V V _{GS} = –5V f = 1MHz			420	pF
C _{oss}	Output Capacitance V _{DS} = 50V V _{GS} = 0 f = 1MHz			175	pF
C _{rss}	Reverse Transfer Capacitance V _{DS} = 50V V _{GS} = 0 f = 1MHz			10.5	pF

* Pulse Test: Pulse Duration = 300 μs , Duty Cycle ≤ 2%

THERMAL DATA

R _{THj-case}	Thermal Resistance Junction – Case	Max. 0.2°C / W 0.4 °C / W -A Version
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